

STPS3045FP

Power Schottky rectifier

Features

- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Low thermal resistance
- Avalanche capability specified

Description

Schottky rectifier suited for switch mode power supply and high frequency DC to DC converters.

Packaged in TO-220 full pack, this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.

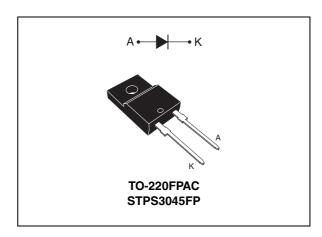


Table 1. Device summary

Symbol	Value
I _{F(AV)}	30 A
V _{RRM}	45 V
T _{j (max)}	175 °C
V _{F (max)}	0.51 V

Characteristics STPS3045FP

1 Characteristics

Table 2. Absolute ratings (limiting values)

Symbol	Parameter	Value	Unit	
V _{RRM}	Repetitive peak reverse voltage	45	V	
I _{F(RMS)}	Forward rms current	45	Α	
I _{F(AV)}	Average forward current $\delta = 0.5$	30	Α	
I _{FSM}	Surge non repetitive forward current $T_p = 10 \text{ ms sinusoidal}, T_c = 25 ^{\circ}\text{C}$		300	Α
P _{ARM}	Repetitive peak avalanche power $t_p = 1 \mu s, T_j = 25 ^{\circ}C$		12500	W
T _{stg}	Storage temperature range	-65 to + 175	°C	
T _j	Maximum operating junction temperat	+ 175	°C	

^{1.} $\frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance parameters

Symbol	Parameter	Value	Unit
R _{th(j-c)}	Junction to case	4.0	°C/W

Table 4. Static electrical characteristics

Symbol	Parameter	Tests conditions		Min.	Тур.	Max.	Unit
I _R ⁽¹⁾ Re	Reverse leakage current	T _j = 25 °C	$V_R = V_{RRM}$			300	μΑ
'R`		T _j = 125 °C			20	60	mA
	((1) Farmond walks as dues	T _j = 25 °C	I _F = 30 A			0.62	
V _F ⁽¹⁾		T _j = 125 °C			0.51	0.57	V
VF V Folward V	Forward voltage drop	T _j = 25 °C	I _F = 60 A			0.79	V
		T _j = 125 °C			0.65	0.72	

^{1.} Pulse test: t_p = 380 μ s, δ < 2%

To evaluate the conduction losses use the following equation:

$$P = 0.42 \text{ x I}_{F(AV)} + 0.0050 \text{ x I}_{F}^{2}_{(RMS)}$$

STPS3045FP Characteristics

Figure 1. Average forward power dissipation Figure 2. Average forward current versus versus average forward current ambient temperature (δ = 0.5)

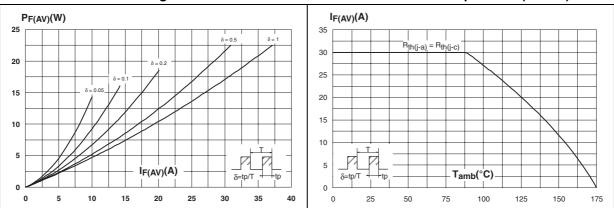


Figure 3. Normalized avalanche power derating versus pulse duration

Figure 4. Normalized avalanche power derating versus junction temperature

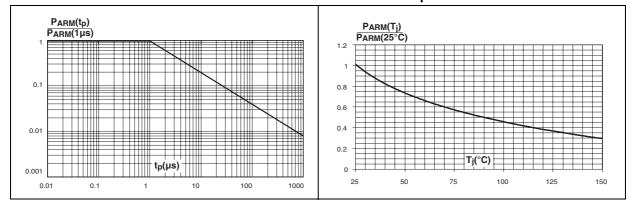
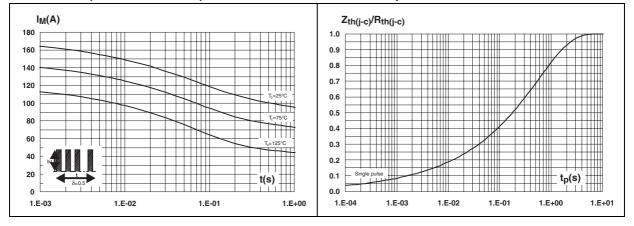


Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values)

Figure 6. Relative variation of thermal impedance junction to case versus pulse duration



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Figure 7. Reverse leakage current versus reverse voltage applied (typical values)

Figure 8. Junction capacitance versus reverse voltage applied (typical values)

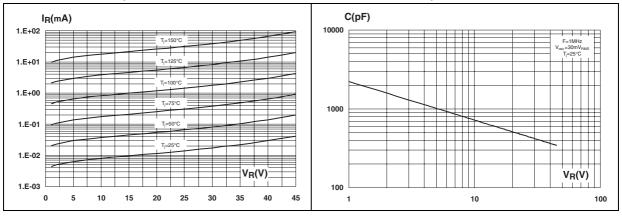
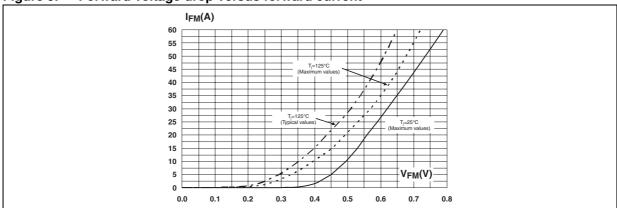


Figure 9. Forward voltage drop versus forward current

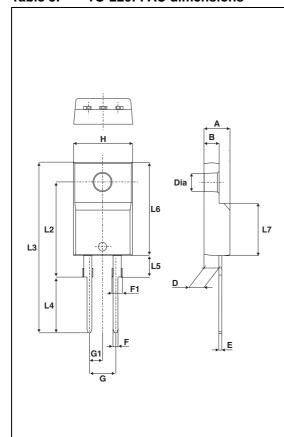


2 Package information

- Epoxy meets UL94,V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Table 5. TO-220FPAC dimensions



	Dimensions					
Ref.	Millimeters		Inc	hes		
	Min.	Max.	Min.	Max.		
Α	4.4	4.6	0.173	0.181		
В	2.5	2.7	0.098	0.106		
D	2.5	2.75	0.098	0.108		
Е	0.45	0.70	0.018	0.027		
F	0.75	1	0.030	0.039		
F1	1.15	1.70	0.045	0.067		
G	4.95	5.20	0.195	0.205		
G1	2.4	2.7	0.094	0.106		
Η	10	10.4	0.393	0.409		
L2	16	Тур.	0.63 Typ.			
L3	28.6	30.6	1.126	1.205		
L4	9.8	10.6	0.386	0.417		
L5	2.9	3.6	0.114	0.142		
L6	15.9	16.4	0.626	0.646		
L7	9.00	9.30	0.354	0.366		
Dia.	3.00	3.20	0.118	0.126		

Ordering information STPS3045FP

3 Ordering information

 Table 6.
 Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS3045FP	STPS3045FP	TO-220FPAC	2.2 g	50	Tube

4 Revision history

Table 7. Document revision history

Date	Revision	Changes
30-Mar-2011	1	Initial issue

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